



Product Change Notification: CENO-11BDML811

Date:

10-Jul-2026

Product Category:

Linear Regulators, Power Management - Power Switches

Notification Subject:

CCB 8023 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for selected MIC2013, MIC2014, MIC2090, MIC2003, MIC2004, MIC2005, MIC2005A, MIC2091, MIC5256, MIC5255, MIC5247, MIC5252, MIC5206, MIC5238, MIC5216 and MIC5317 device families available in 5L SOT-23 package at STAR assembly site.

Affected CPNs:

[CENO-11BDML811_Affected_CPN_07102026.pdf](#)

[CENO-11BDML811_Affected_CPN_07102026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for selected MIC2013, MIC2014, MIC2090, MIC2003, MIC2004, MIC2005, MIC2005A, MIC2091, MIC5256, MIC5255, MIC5247, MIC5252, MIC5206, MIC5238, MIC5216 and MIC5317 device families available in 5L SOT-23 package at STAR assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Stars Microelectronics (Thailand) Public Company	Stars Microelectronics (Thailand) Public Company	No

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

March 18, 2026: Issued initial notification.

July 10, 2026: Reissued the initial notification to update the Leadframe paddle size (pre-change) from 64 × 45 mil to 72 × 52 mil, updated the LF design to "No change," and removed the "Pre- and Post-Change Summary" attachment since there is no change to the Leadframe design. Updated the LF part number to MLEP00026MIC-T.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CENO-11BDML811-Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

MIC5238-1.0YM5-TR
MIC5238-1.1YM5-TR
MIC5216-3.6YM5-TR
MIC5216-3.3YM5-TR
MIC5216-5.0YM5-TR
MIC5216-2.5YM5-TR
MIC5238-1.3YM5-TR
MIC5206-2.5YM5-TR
MIC5206-2.7YM5-TR
MIC5206-4.0YM5-TR
MIC5255-2.9YM5-TR
MIC5255-3.2YM5-TR
MIC5256-1.5YM5-TR
MIC5255-2.5YM5-TX
MIC5255-2.5YM5-TR
MIC5256-1.8YM5-TR
MIC2013-0.8YM5-TR
MIC2013-1.2YM5-TR
MIC2014-0.5YM5-TR
MIC2003-0.8YM5-TR
MIC5256-2.9YM5-TR
MIC5256-3.0YM5-TR
MIC5256-3.1YM5-TR
MIC5255-3.0YM5-TR
MIC5206-5.0YM5-TR
MIC2005-1.2LYM5-TR
MIC5317-1.2YM5-TR
MIC5317-1.5YM5-TR
MIC5317-2.5YM5-TR
MIC5317-2.8YM5-TR
MIC5317-3.3YM5-TR
MIC5317-1.8YM5-TR

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MIC5317-3.0YM5-TR

MIC2013-0.5YM5-TR

MIC5247-2.4YM5-TR

MIC2014-0.8YM5-TR

MIC2014-1.2YM5-TR

MIC2090-2YM5-TR

MIC2003-0.5YM5-TR

MIC2004-1.2YM5-TR

MIC2005-0.5LYM5-TR

MIC2003-1.2YM5-TR

MIC2004-0.5YM5-TR

MIC2005A-1YM5-TR

MIC2005A-2YM5-TR

MIC2004-0.8YM5-TR

MIC2090-1YM5-TR

MIC2091-1YM5-TR

MIC2091-2YM5-TR

MIC5256-3.3YM5-TR

MIC5247-1.5YM5-TR

MIC5247-1.8YM5-TX

MIC5247-1.8YM5-TR

MIC5247-1.85YM5-TR

MIC5247-2.0YM5-TR

MIC5256-2.5YM5-TR

MIC5255-3.3YM5-TR

MIC5255-2.7YM5-TR

MIC5255-2.75YM5-TR

MIC5255-2.8YM5-TR

MIC5252-1.5YM5-TR

MIC5252-1.8YM5-TR

MIC5252-2.5YM5-TR

MIC5252-2.8YM5-TR

MIC5252-2.85YM5-TR

MIC5252-3.0YM5-TR

MIC5252-4.75YM5-TR

MIC5206-3.0YM5-TR

MIC5206-3.2YM5-TR

MIC2005-0.8LYM5-TR

MIC5206-3.3YM5-TR

MIC5206-3.6YM5-TR

MIC5206-3.8YM5-TR

MIC5255-2.6YM5-TR

MIC5255-2.85YM5-TR

MIC5256-2.6YM5-TR

MIC5256-2.7YM5-TR

MIC5256-2.8YM5-TR

MIC5256-2.85YM5-TR

MIC5255-3.1YM5-TR

MIC5255-3.3YM5-TX



QUALIFICATION PLAN SUMMARY

PCN #: CENO-11BDML811

**Date:
February 26, 2026**

**Qualification of palladium coated copper with gold flash (CuPdAu)
as new bond wire material for selected MIC2013, MIC2014,
MIC2090, MIC2003, MIC2004, MIC2005, MIC2005A, MIC2091,
MIC5256, MIC5255, MIC5247, MIC5252, MIC5206, MIC5238,
MIC5216 and MIC5317 device families available in 5L 8L SOT-23
package at STAR assembly site.**

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for selected MIC2013, MIC2014, MIC2090, MIC2003, MIC2004, MIC2005, MIC2005A, MIC2091, MIC5256, MIC5255, MIC5247, MIC5252, MIC5206, MIC5238, MIC5216 and MIC5317 device families available in 5L 8L SOT-23 package at STAR assembly site.

CCB No.: 8023

Misc.	Assembly site	STAR
	BD Number	BD-004231 rev.01
	MP Code (MPC)	21822Y6BXA02
	Part Number (CPN)	MIC5238-1.1YM5-TR
	MSL information	MSL-1@260C
	Assembly Shipping Media	T/R
	Base Quantity Multiple (BQM)	3,000 units
	Reliability Site	MTAI
Lead-Frame	Paddle size	72 x 52 mil
	Material	C194
	DAP Surface Prep	NiPdAu
	Treatment	RT UPG
	Process	Stamp
	Part Number	MLEP00026MIC-T
	Lead Plating	NiPdAu
	Strip Size	83x270 mm
	Strip Density	960
Bond Wire	Material	CuPdAu
Die Attach	Part Number	84-1LMISR4
	Conductive	Yes
MC	Part Number	G700
PKG	Package Type	SOT-23
	Pin/Ball Count	5

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5		STAR	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Backward Solderability	J-STD-002D ;Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.	22	5	1	27	> 95% lead coverage	5		STAR	
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5		STAR	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5		STAR	30 bonds from a min. 5 devices.
Wire Sweep									STAR	
Physical Dimmensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5		STAR	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5		STAR, MTAI	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C	45	5	3 (Cu wire qual)	150 (Cu wire qual)	0	10	STAR	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1 @260C	231	15	3	738	0	15	STAR	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	STAR	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHASt	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	STAR	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at room temp (25C); 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	STAR	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.